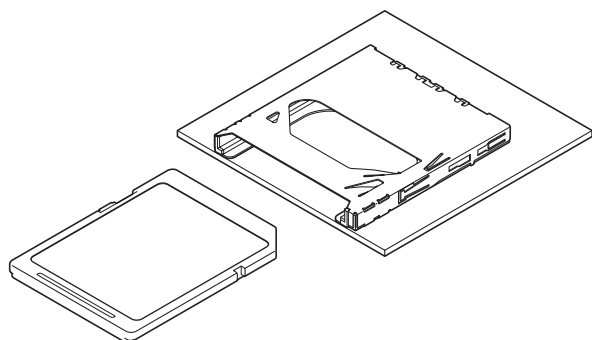


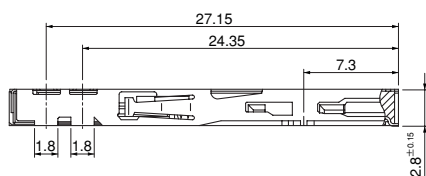
# SDK CONNECTOR



**This connector is designed for SD Card & MMC (Multi media card), complying with the SD Card Association standard, and is with the switch for Write-protection & Card-detection. And due to Push-push mechanism design, its card can be easily ejected by push-push operation.**

- Space saving design
- The amount of card ejection
- Outstanding durability
- Prevention of reverse card insertion

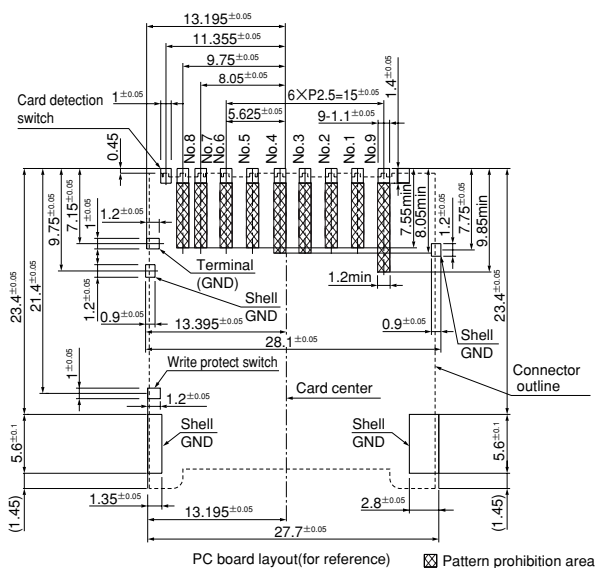
PC board layout (viewed from component side) and Assembly layout



Note: 1. Tolerances are non-cumulative:  $\pm 0.05\text{mm}$  for all centers.  
2. The dimensions above should serve as a guideline. Contact JST for details.

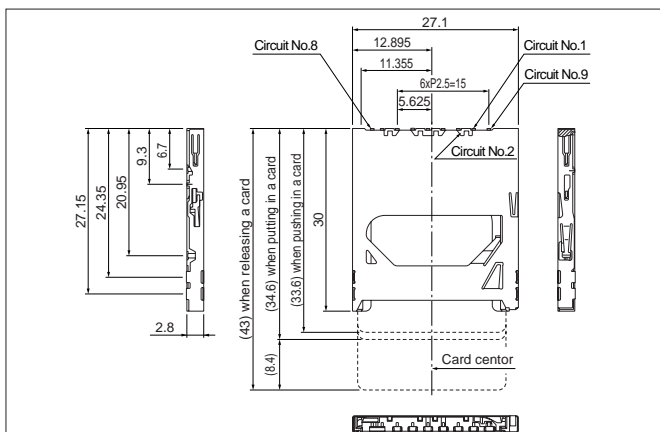
## Specifications

- Current rating: 0.5A AC, DC
- Voltage rating: 5V AC, DC
- Temperature range:  $-25^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$   
(including temperature rise in applying electrical current)
- Recommendatory PC board thickness: 0.6mm to 1.0mm  
[When it is mounted on the FPC, recommendable reinforcing layer thickness is 0.6mm min.]
- Contact resistance:  
(Signal part) Initial value/30m  $\Omega$  max.  
After environmental testing/60m  $\Omega$  max.  
(Switch part) Initial value/100m  $\Omega$  max.  
After environmental testing/100m  $\Omega$  max.
- Insulation resistance: 1,000M  $\Omega$  min. at 500V DC
- Withstanding voltage: 500V AC/minute
- \* RoHS compliant products are published.
- \* Refer to "General Instruction and Notice when using Terminals and Connectors" at the end of this catalog.
- \* Contact JST for details.



PC board layout(for reference) Pattern prohibition area

## Connector



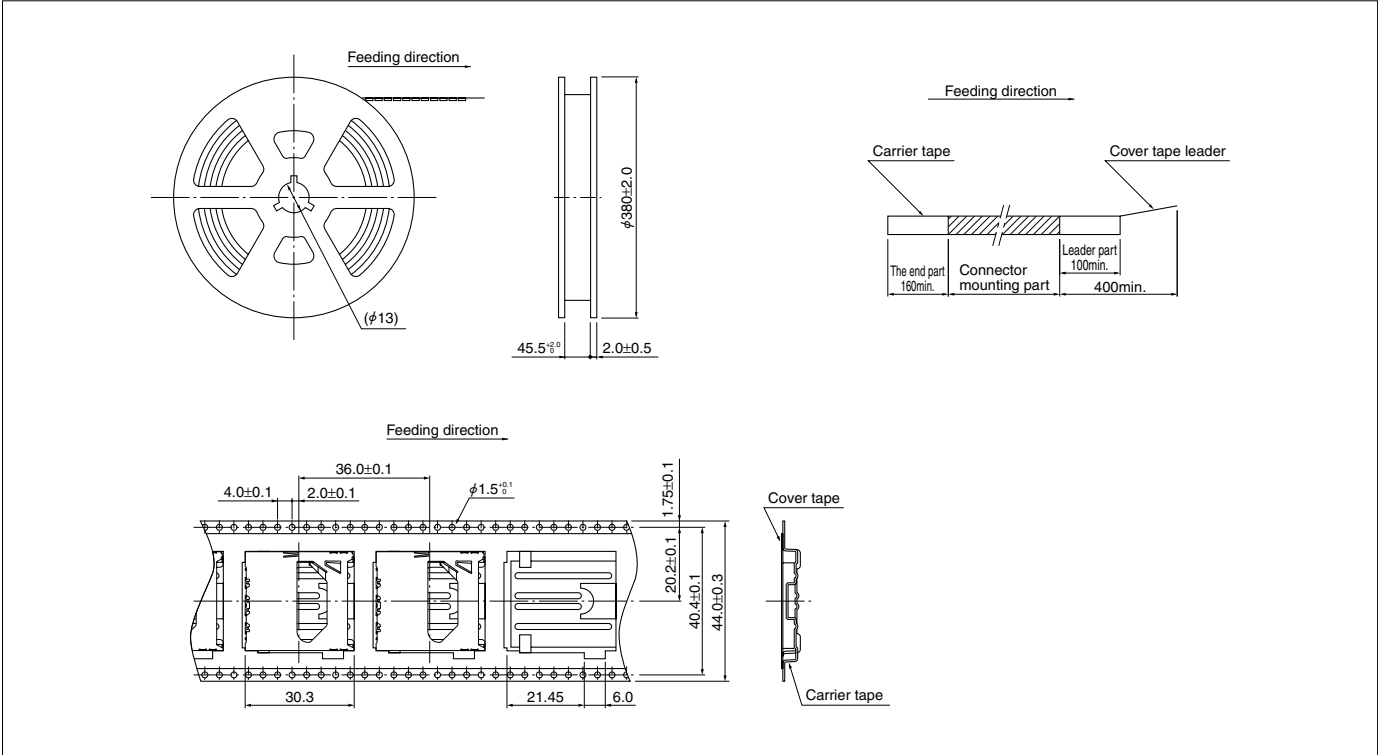
Model No.	Q'ty / reel
SDK-9BNS-K13-GN-TB	450

### Material and Finish

Housing, Guide: Heat resisting resin, UL94V-0  
 Contact: Copper alloy, nickel-undercoated, selective gold-plated, selective tin-plated (reflow treatment)  
 Terminal: Copper alloy, nickel-undercoated, gold-plated  
 Card detection switch: Copper alloy, nickel-undercoated, gold-plated  
 Write protect switch: Copper alloy, nickel-undercoated, selective gold-plated, selective tin-plated (reflow treatment)  
 Card lock: Copper alloy, tin-plated  
 Joint rod, Spring: SUS  
 Shell: SUS, Solder tail/ selective nickel-undercoated, tin-plated (reflow treatment)

**RoHS compliance** This product displays (LF)(SN) on a label.  
This products listed above are supplied on embossed-tape.

## Taping specifications



Note: 1. Specifications conform to JIS C 0806. The tape width, connector loading recess square hole dimensions, etc. are determined by the number of circuits and external shape of the connector to be loaded.  
 2. Specifications are subject to change without prior notice.